



Huawei Technologies Co., Ltd.

2015-01-14

Federal Communication Commission
Equipment Authorization Division, Application Processing Branch
7435 Oakland Mills Road
Columbia, MD 21048

Certification and Engineering Bureau
Industry Canada
Spectrum Engineering Branch
3701 Carling Avenue, Building 94
Ottawa, Ontario K2H 8S2

PCII Request / Re-assessment

< MU509-c >, FCC ID: < QISMU509C > granted on < 2010-11-24 >

TO WHOM IT MAY CONCERN

Pursuant to CFR § 2.1043 and RSP-100, < Huawei Technologies Co., Ltd. > hereby requests a Permissive Change Class II / Re-assessment.

Reason:

Modifications:

- new RF component

The following new exhibits will be uploaded:

- Test report on radiated measurements
- RF Exposure Info
- External, internal Photos,
- Block Diagram, Schematics, Parts list and Tune Up Info
- Operational Description, User Manual

Differences between the MU509-c(old) and the MU509-c(new)

The old Band5 RF PA, Band2 RF PA, RF Switch and MCP were already EOL, so MU509-c has to apply new Band5 RF PA, Band2 RF PA, RF Switch and MCP.

The new amplifier chip is pin compatible to the old one and supports the same basic functions. Any change made does not influence the RF parameters as is confirmed by the provided test reports.

The differences between the old and new RF component have been listed in Table 1.
Table 1 the differences between the old and new RF components.

Items	Part Number	Suppliers	insertion attenuation @TX-ANT	insertion attenuation @ANT- RX	Isolation @ TX-RX
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Old	ACPM-5205-TR1	Avago	27	27.5	NA
New	RF7305TR7HW	RFMD	29	27.5	NA
Old	ACPM-5202-TR1	Avago	28.5	28	NA
New	RF7302TR7HW	RFMD	28	28.5	NA
Old	LMSP4LMA-550	Murata	NA	NA	NA
New	RF1194ATR13HW	RFMD	NA	NA	NA
conclusion	/	/	Almost same	Almost same	Same

Table 2 The differences between the old and new MCP

Items	Part Number	Suppliers	Memory Combination	Operation Voltage	Density	Package
old MCP	H9DA1GH25HAMMR-4EM	HYNIX	NAND Flash	1.8V	1Gb(64Mx16) 256Mb(16Mbx16)	BGA 130
new MCP	FM64D1G12A-5BAGE	ESMT	NAND Flash	1.8V	1G(64M*16bit) 512M (32M*16bit)	BGA 130
new MCP	MT29C1G12MAAJV AMD-5 IT	MICRON	NAND Flash	1.8V	1G(64M*16bit) 512M (32M*16bit)	BGA 130
conclusion	/	/	same	same	different	same

Sincerely,

Zhang Xinghai

EMC Laboratory Manager

For and Behalf of:

Huawei Technologies Co., Ltd.



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